

2815

PTO/SB/21 (08-00)

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Approved for use through 10/31/2002. OMB 0651-0031

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| <b>TRANSMITTAL FORM</b><br><i>(to be used for all correspondence after initial filing)</i> | Application Number   | 09/585,682             |                           |
|  | Filing Date          | June 1, 2000           |                           |
|  | First Named Inventor | Ko et al.              |                           |
|  | Group Art Unit       | 2815                   |                           |
|  | Examiner Name        | C. Chu                 |                           |
|  |                      | Attorney Docket Number | 2269-3526.2US (97-1136.2) |

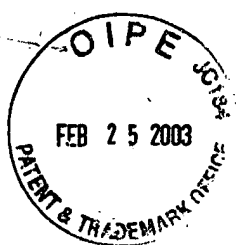
| ENCLOSURES (check all that apply)   |   |  |
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| <input checked="" type="checkbox"/> Duplicate copy of this transmittal sheet in the event that additional filing fees are required under 37 C.F.R. § 1.16 | <input type="checkbox"/> Supplemental Information Disclosure Statement; PTO/SB/08A (08-00); copy of cited references and Check No. in the amount of \$180.00  | <input type="checkbox"/> Terminal Disclaimer                         |
| <input type="checkbox"/> Preliminary Amendment  | <input type="checkbox"/> Associate Power of Attorney  | <input type="checkbox"/> Terminal Disclaimer                         |
| <input type="checkbox"/> Response to Restriction Requirement/Election of Species Requirement dated  | <input type="checkbox"/> Petition for Extension of Time and Check No. in the amount of \$   |  |
| <input checked="" type="checkbox"/> Amendment under 37 C.F.R. § 1.111 in response to office action dated November 20, 2002                                | <input type="checkbox"/> Petition   |  |
| <input type="checkbox"/> Amendment under 37 C.F.R. § 1.116 in response to final office action dated   | <input type="checkbox"/> Fee Transmittal Form   | <input type="checkbox"/> Other Enclosure(s) (please identify below): |
| <input type="checkbox"/> Additional claims fee - Check No. in the amount of \$  | <input type="checkbox"/> Certified Copy of Priority Document(s)   |  |
| <input type="checkbox"/> Letter to Chief Draftsman and copy of FIGS. with changes made in red   | <input type="checkbox"/> Assignment Papers (for an Application)   |  |
| <input type="checkbox"/> Transmittal of Formal Drawings   | Remarks   |  |
| <input type="checkbox"/> Formal Drawings ( sheets)  | The Commissioner is authorized to charge any additional fees required but not submitted with any document or request requiring fee payment under 37 C.F.R. §§ 1.16 and 1.17 to Deposit Account 20-1469 during pendency of this application. |  |

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| Firm or Individual name                    | Brick G. Power    |
| Signature                                  |                   |
| Date                                       | February 20, 2003 |

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| Typed or printed name   | Deidra Pfeil      |
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| Date  | February 20, 2003 |

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PATENT 3/4/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Ko et al.

Serial No.: 09/585,682

Filed: June 1, 2000

**For:** SEMICONDUCTOR DEVICE  
HAVING A SUBSTRATE, AN UNDOPED  
SILICON OXIDE STRUCTURE, AND AN  
OVERLYING DOPED SILICON OXIDE  
STRUCTURE, AND AN OVERLYING  
DOPED SILICON OXIDE STRUCTURE  
WITH A SIDE WALL TERMINATING AT  
THE UNDOPED SILICON OXIDE  
STRUCTURE

Confirmation No.: 7481

Examiner: C. Chu

Group Art Unit: 2815

Attorney Docket No.: 3526.2US (97-1136.2)

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February 20, 2003  
Date

Signature

Deidra J. Pfeil  
Name (Type/Print)

AMENDMENT UNDER 37 C.F.R. § 1.111

Box Non Fee Amendment  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

This Amendment is being filed in response to the Office Action mailed on November 20, 2002, the three-month shortened statutory period for response to which expires on February 20, 2003.

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IN THE TITLE:

Please replace the title, both on the cover page of the above-referenced application and at page 2, lines 1 through 4, with the following:

**SEMICONDUCTOR DEVICE HAVING A SUBSTRATE, AN UNDOPED SILICON  
OXIDE STRUCTURE, AND AN OVERLYING DOPED SILICON OXIDE STRUCTURE  
WITH A SIDEWALL TERMINATING AT THE UNDOPED SILICON OXIDE  
STRUCTURE**